

Weekly Report

1. module production
2. wire bonding
3. shipping document
4. Lab Management
5. Others

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Module Production Summary

Modules for double sided stave:

RAL_SS11 = HCC 5/8 -> built, ready for powerboard

RAL_SS12 = HCC 9/17 (104_3, 104_7) -> built, ready for bonding->**finish bonding->next step: test, power board**

RAL_SS13 = HCC 6/12 (102_3, 104_5) -> waiting for assembly->**finish assembly**

RAL_SS14 = HCC 18/16 (104_1, 104_6) -> waiting for 104_1->**finish back-end wire bonding and test**

RAL_SS15 = HCC 19/20 (104_0, 110_X) -> waiting for 104_0 and 111_X

Hybrids to do:

Panel_102_Hybrid3_HCC6 -> test before module building->**finished test**

Panel_104_Hybrid5_HCC12 -> ready for module building

Panel_104_Hybrid6_HCC16 -> ready for module building

Panel_104_Hybrid1_HCC18 -> needs wire bonding and test before module building->**finish bonding and test**

Panel_110_HybridX_HCC20 -> needs assembly, wire-bonding and test before module building

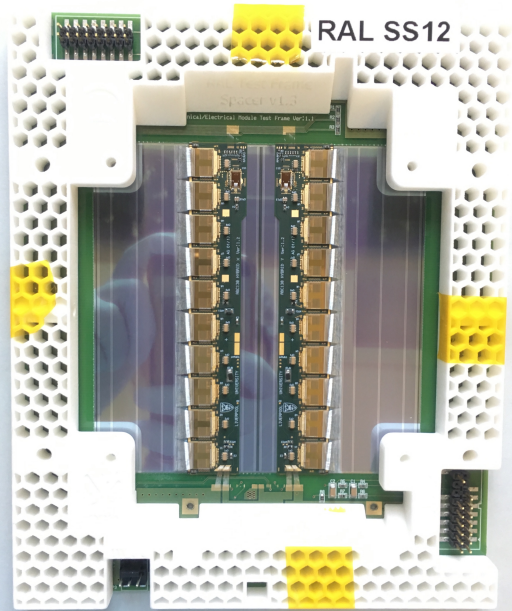
Panel_104_Hybrid0_HCC19 -> needs assembly, wire-bonding and test before module building

Plan:

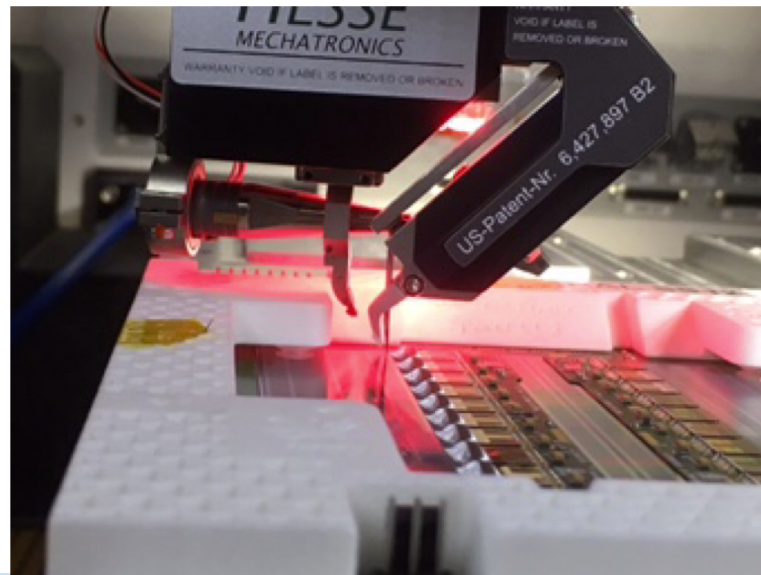
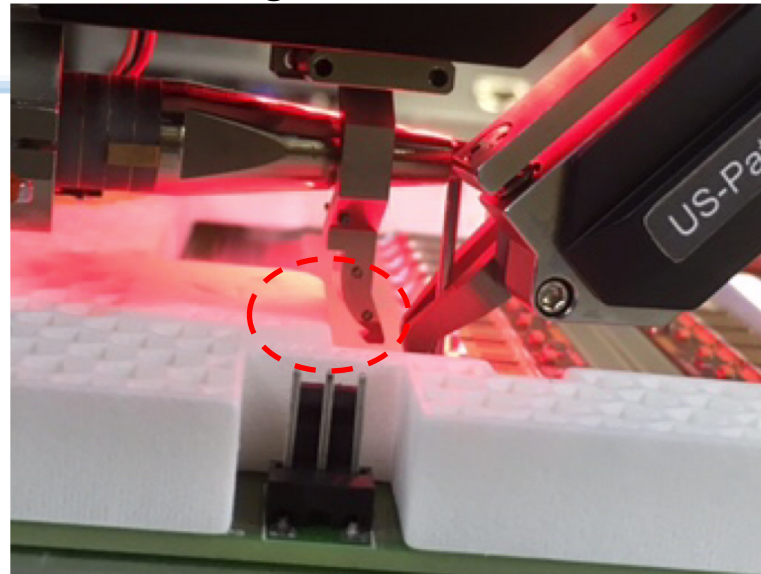
1. — Bond Panel_104_Hybrid1_HCC18
 2. — Bond RAL_SS12
 3. — Test Panel_104_Hybrid1_HCC18 and Panel_102_Hybrid3_HCC6
 4. — Glue Panel_102_Hybrid3_HCC6 and Panel_104_Hybrid5_HCC12 to sensor
 5. Glue Panel_104_Hybrid6_HCC16 and Panel_104_Hybrid1_HCC18 to sensor (this Friday and next week...)
 6. Assemble Panel_110_HybridX_HCC20 and Panel_104_Hybrid0_HCC19 (next week...)
 7. Test Panel_110_HybridX_HCC20 and Panel_104_Hybrid0_HCC19
 8. Glue Panel_110_HybridX_HCC20 and Panel_104_Hybrid0_HCC19 to sensor
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Wire Bonding: RAL_SS12

- write front-end program: old patch short strip (74.5um)
- bond front-end:
 - both hybrids use the same program, so need to rotate module
 - plan to write a new program for short strip module, when is new patch short strip (75.5um)
- write and bond data-power between hybrid and frame
 - without power board now
 - check the differences between with and without power board
- next step:
 - test
 - glue power board
 - wire bonding the power-data
 - test



quite close to the white frame
- next design will make it clearance



Document and Lab Management

➤ shipping document

- discuss with Xin and Craig
- update the first version of shipping document
<https://docs.google.com/document/d/1974A3NSu6eMwxvYAaxC1QPO2a2ZECfseSSnPwzzOpE/edit#heading=h.e2tsdxd1gp51>

➤ Lab Management

- slim wedge: about 50GBP/wedge
 - TD prepare to buy 20, they can give us 1 or 2 or several wedges if it is necessary.
 - but Craig said IHEP also not ready now
 - next step??
 - glue dispense machine
- ## ➤ finish the annual evaluation of postdoc

Thank you !